

# Projection electron microscopic image simulation for EUV mask pattern inspection

Susumu Iida, Tsuyoshi Amano, Ryoichi Hirano, Tsuneo Terasawa and Hidehiro Watanabe  
EUVL Infrastructure Development Center, Inc.

## Summary

We are developing a novel projection electron microscope (PEM) technique for detecting less than 18 nm in size defects on hp 16 nm EUV mask. In order to predict the optimal conditions for inspection, we are also developing an advanced simulation technique taking into account imaging electron optics (EO).

- ◆ Designed imaging EO data can be imported to the simulator “CHARIOT™”, improved by Abeam Technologies Inc..
- ◆ Electron trajectories and focused images can be simulated as the imaging EO designed.

## Motivation

Design of imaging EO determines the quality of PEM image, besides, the characteristics of EUV mask PEM image depends on the geometry, the materials and the charging of the mask.

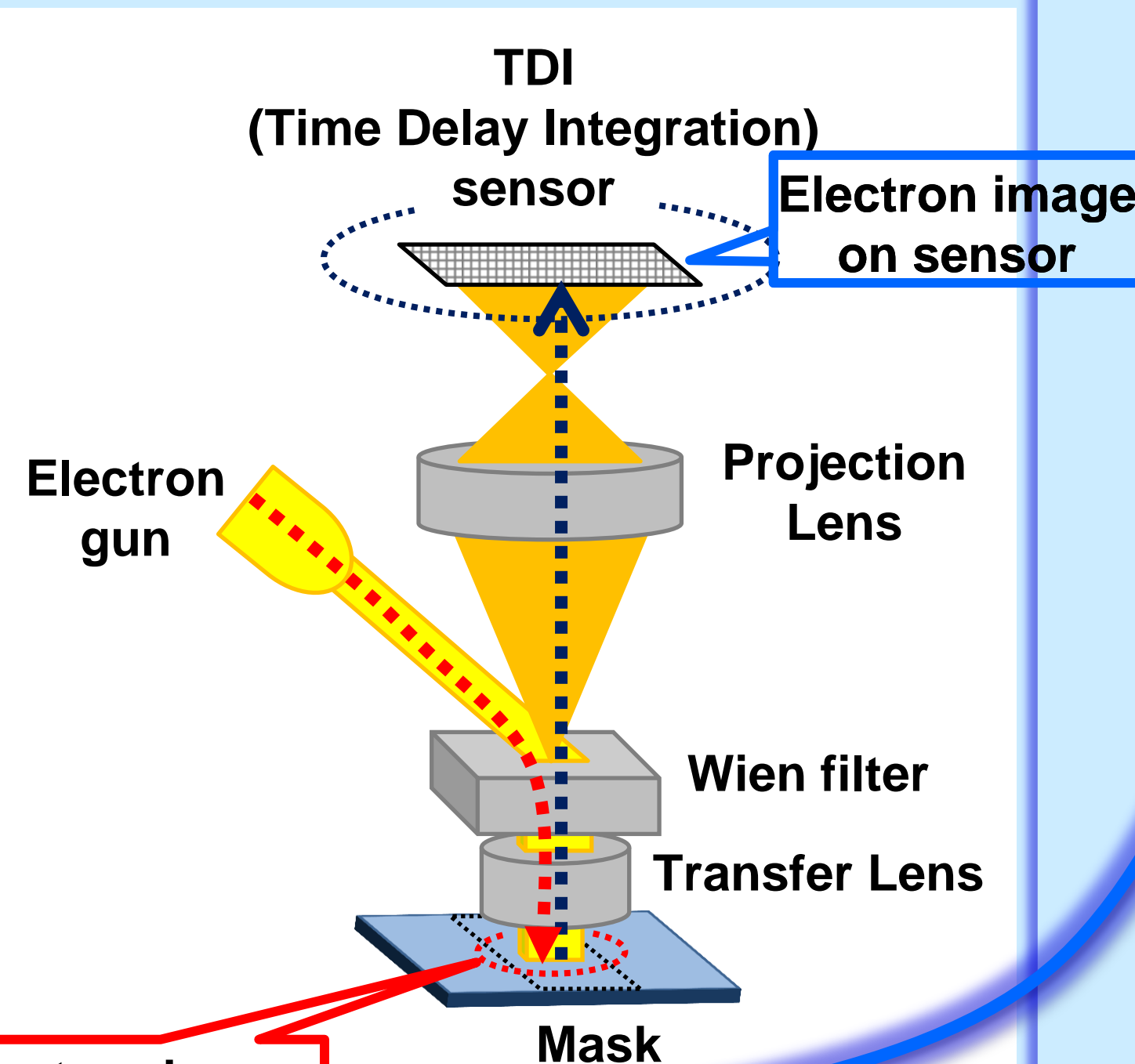
By tracing the electron trajectories, we can optimize the parameter such as landing energy, current density and imaging EO parameter. Therefore, we modified the CHARIOT software to import electromagnetic lens configuration.

## Advantage of taking into account imaging EO

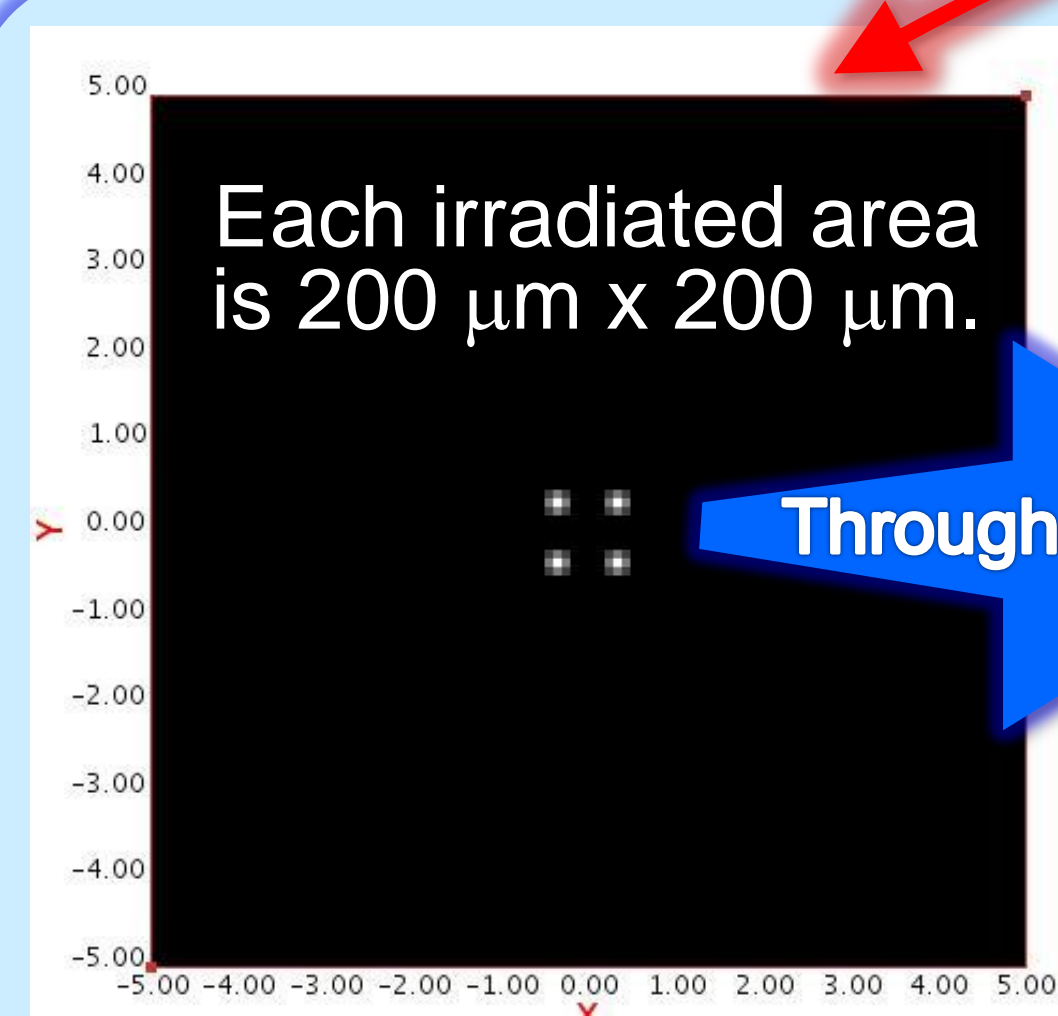
Simulation	Near mask	On sensor
Aberration	no	yes
aperture size	no	yes
Transmittance	no	yes
energy filtering effect	yes by adjusting energy range of detector	yes
SE <sub>III</sub>	no	yes but not yet in this presentation

SE<sub>III</sub>: produced by high energy BSE which strike pole pieces and other solid objects near the specimen.

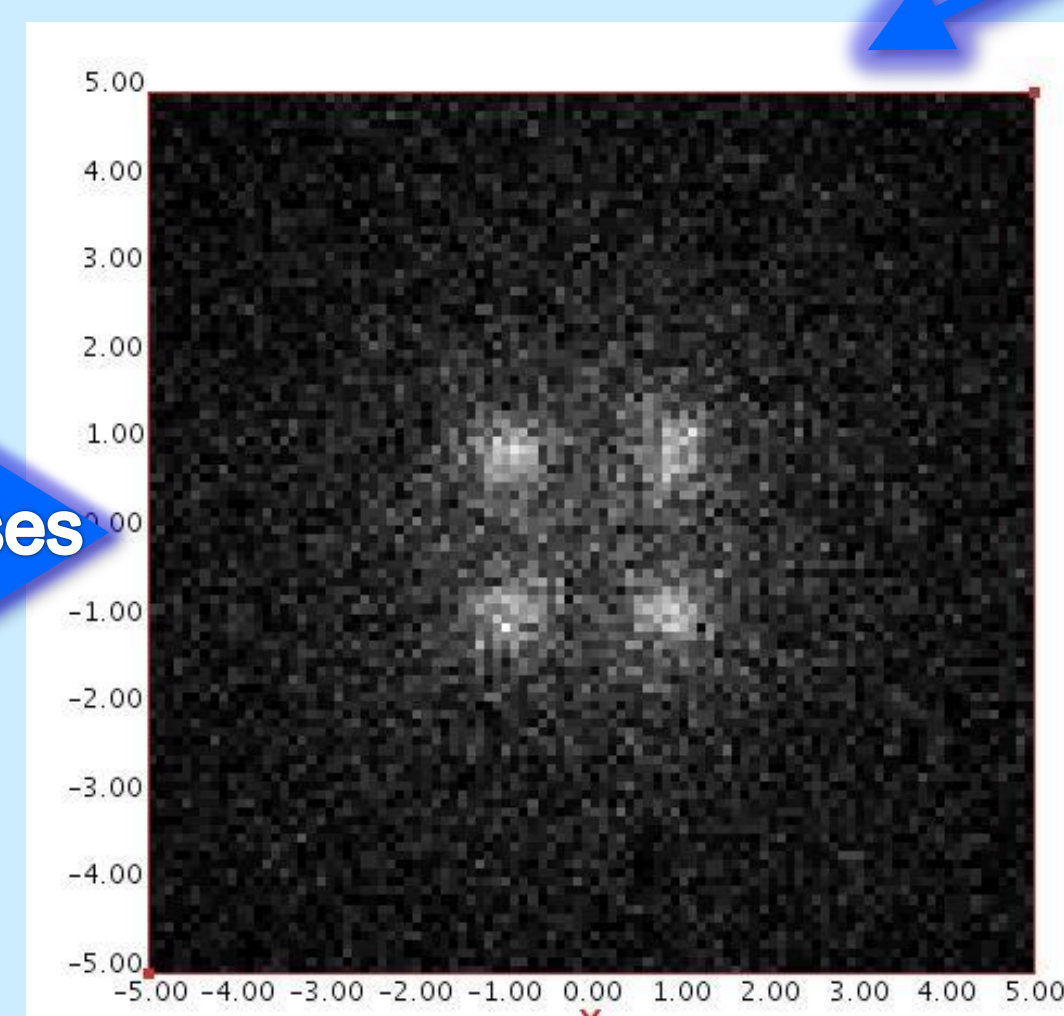
## Schematic illustration of Projection Electron Microscope (PEM)



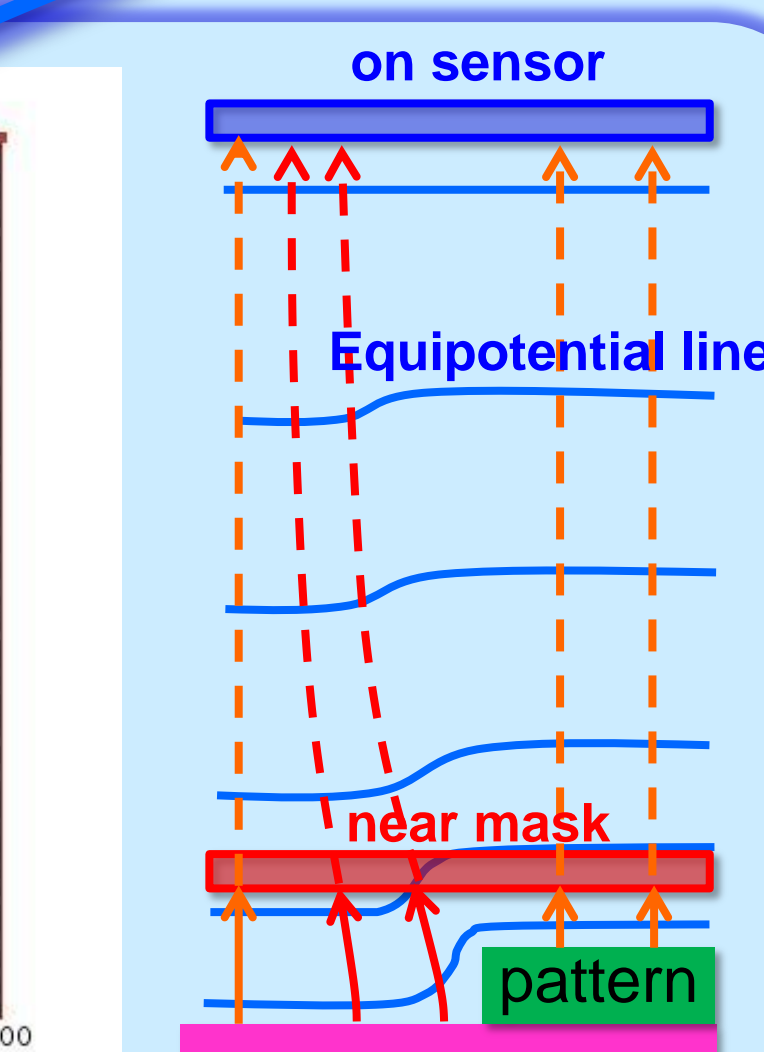
Electron image near mask



**Near field image**  
1nm height  
above the sample

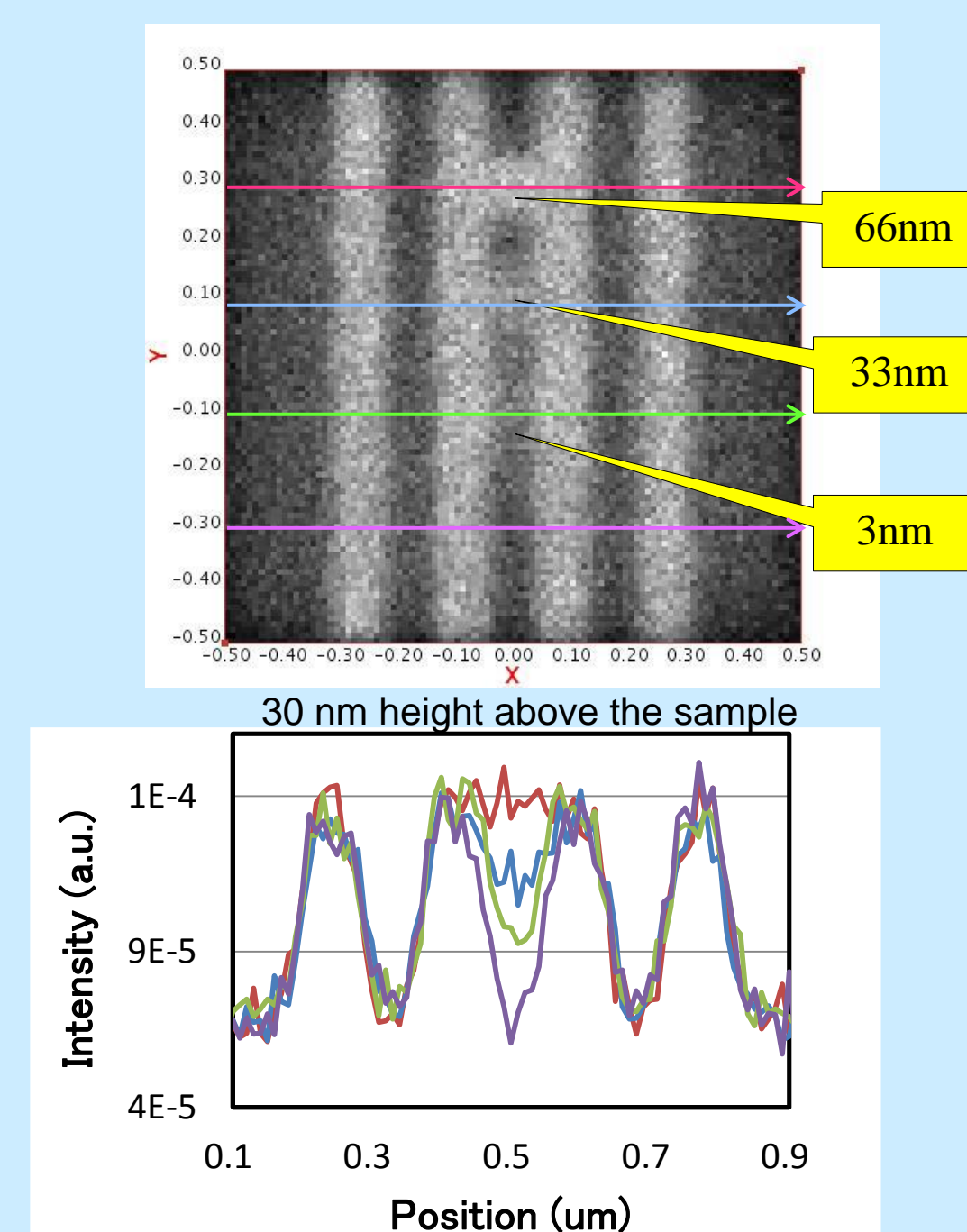


**Focused image**  
~200 nm height  
above the sample.



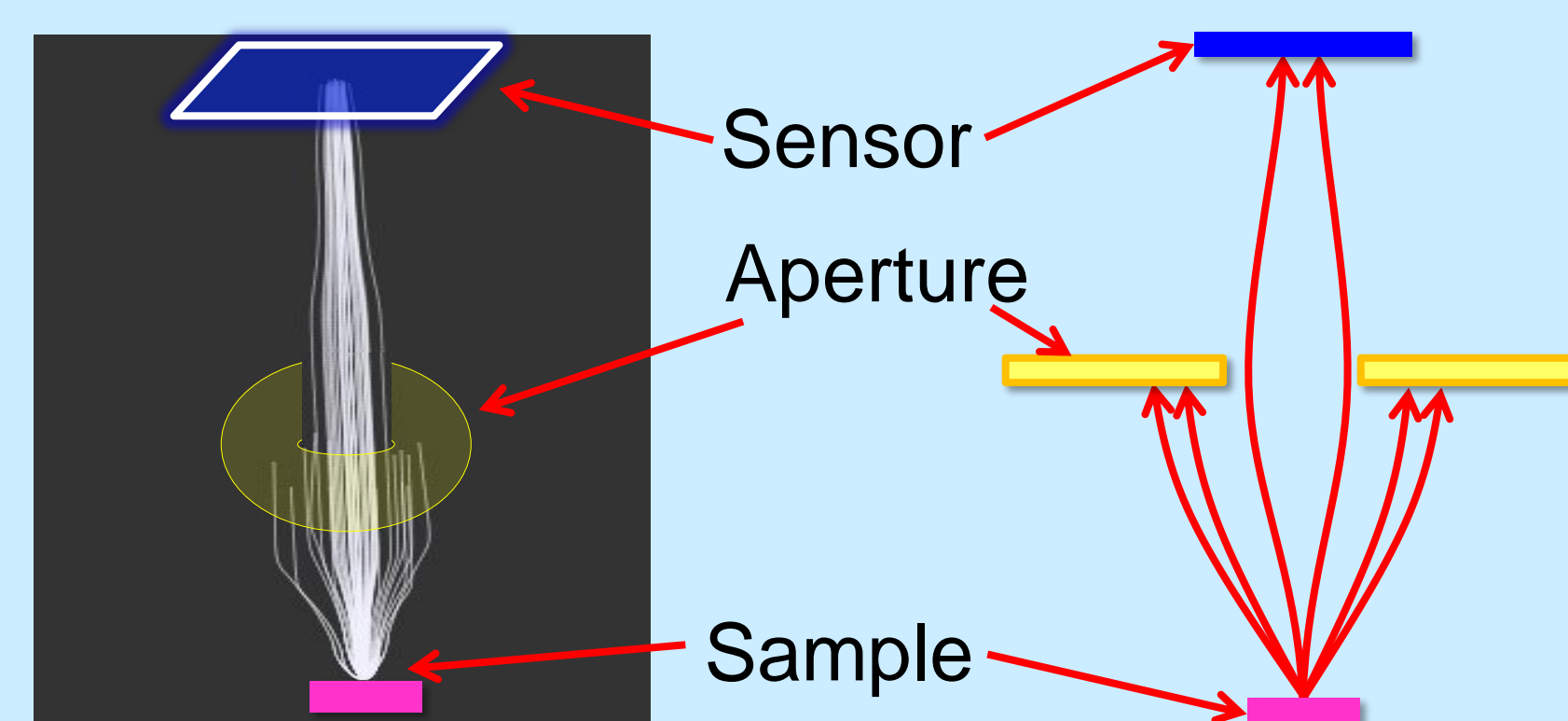
Schematic illustration  
of affected electron  
trajectories by  
potential distribution

We can examine the influence of aberration, noise and etc. on the image. Also, the electron trajectories are affected by the potential distribution generated by mask geometry, charging effect and external electric field. These phenomena can be investigated by using this technique.



Identification of  
residual-type defects

We have already investigated the simulated **near field image** of residual-type defects with various thicknesses<sup>1-2)</sup>. The **focused image** is now being examined.



Electron trajectories can be cut by aperture stop

We can examine the influence of the size and shape of an aperture and the transmittance on the image. Undesirable electrons, which leads to the aberration and low MTF of the image, can be eliminated by the aperture.

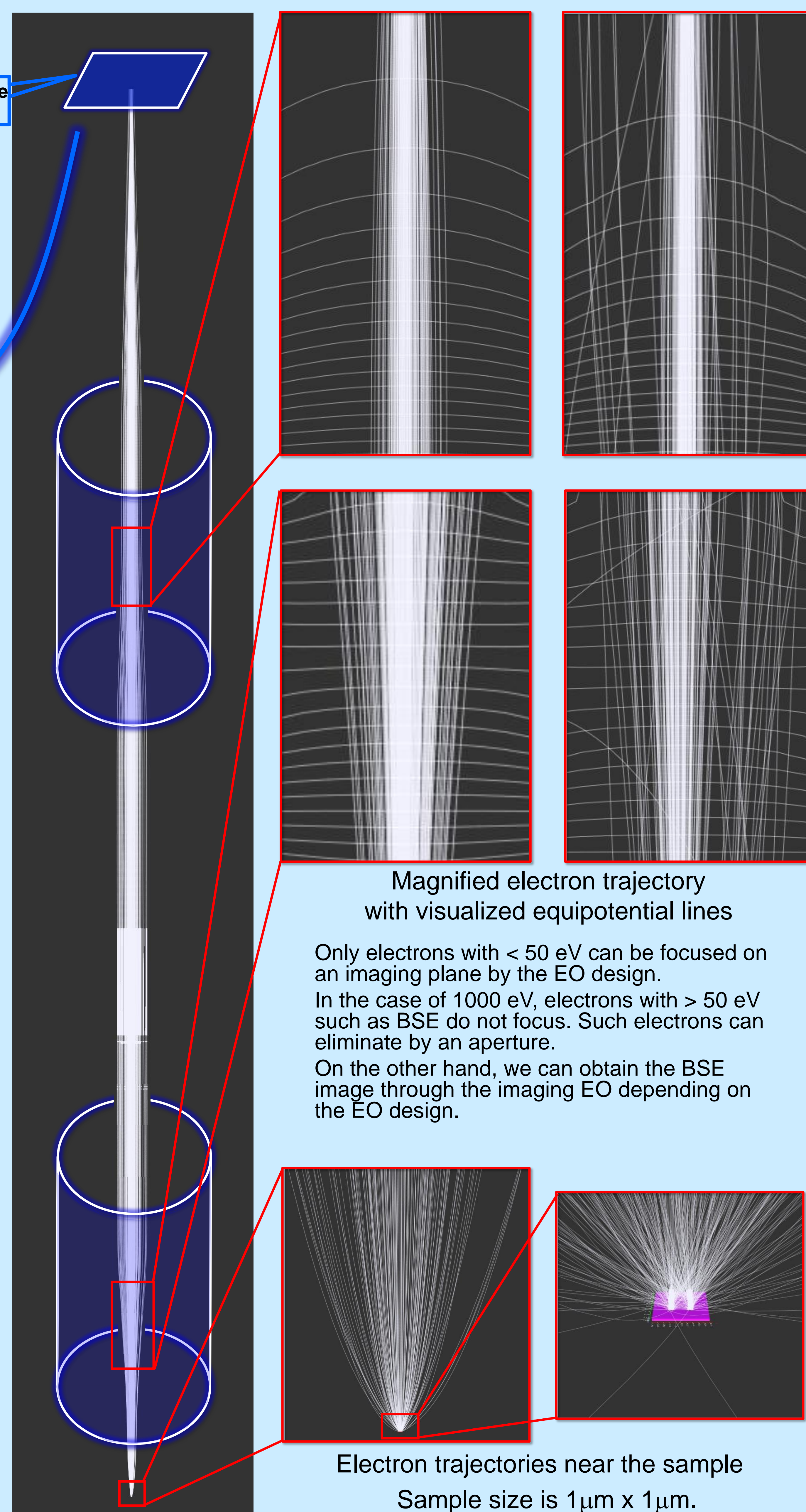
## Simulation tool

CHARIOT Monte Carlo software (Abeam Technologies, Inc.) with 72 cores was installed in an all-in-one server computer, Proliant DL 980 G2 (Hewlett-Packard) with 80 cores.

## Electron trajectories through the imaging EO without aperture

Landing energy < 50 eV

Landing energy  
1000 eV



Electron trajectories  
generated from the sample

Electron trajectories near the sample  
Sample size is 1 μm x 1 μm.

Electrons are accelerated and focused on the imaging plane by passing through the imaging EO.

Reference:

- 1) S. Iida et al. J. Vac. Sci. Technol. B 30, 06F503 (2012)
- 2) T. Amano et al. J. Vac. Sci. Technol. B 30, 06F501 (2012)

## Future work

Improvement of the calculation accuracy and the simulation speed.  
Implementation of taking into account SE<sub>III</sub>.

## Acknowledgement

EBARA corporation Mr. T. Murakami for his technical advice.

Hewlett-Packard Japan, Ltd. Ms. E. Asazaka and EIDEC Dr. Y. Arisawa for preparing our server computer.

Abeam Technologies Inc. Dr. S. Babin and Dr. S. Borisov for developing this technique in CHARIOT™ and for their helpful technical suggestions.

This work is supported by New Energy and Industrial Technology Development Organization (NEDO)

EUVL Symposium 2012

